Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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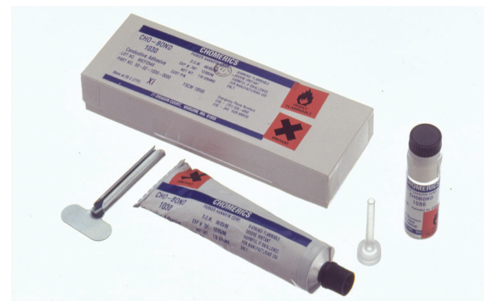
# CHO-BOND® 1030

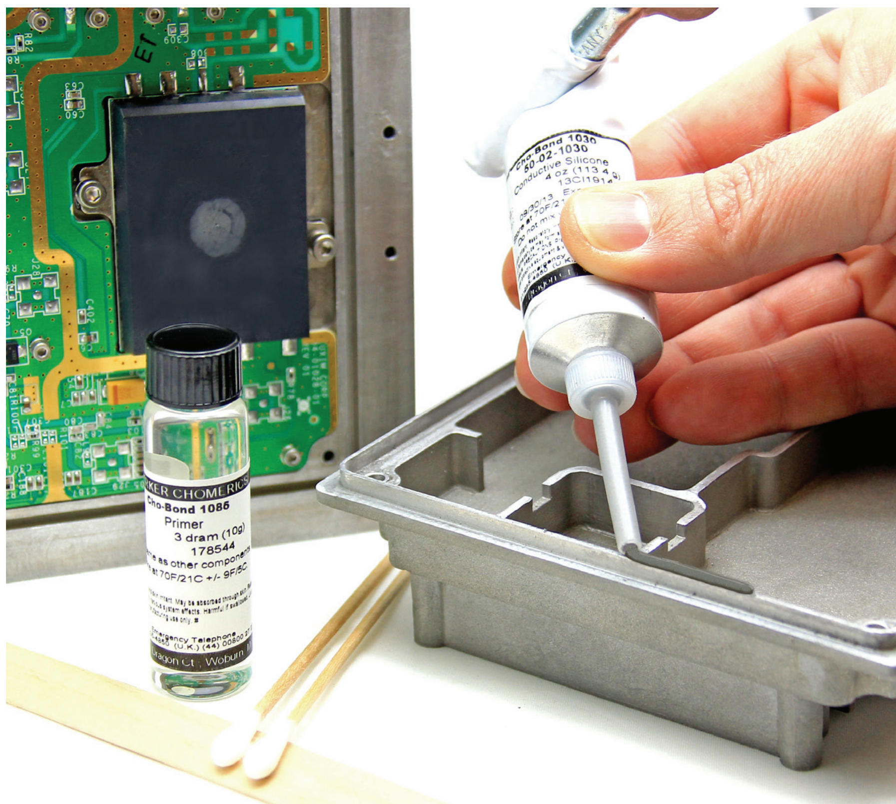
## ONE COMPONENT FLEXIBLE ELECTRICALLY CONDUCTIVE SILICONE ADHESIVE



### Customer Value Proposition:

CHO-BOND 1030 is a silver plated copper filled, one-component conductive silicone designed for applications where a flexible, strong, conductive electrical bond must be achieved. CHO-BOND 1030 greatly simplifies the problem of bonding conductive silicone EMI gaskets to metal substrates. It is formulated for relatively small bond lines (less than 0.010 inches (0.25mm)), and should not be used as an EMI caulk where bond lines are greater than 0.10 inches (0.25 mm). No volatile organic compounds (VOCs) and minimal shrinkage upon curing make CHO-BOND 1030 a good choice for a variety of commercial and military applications. CHO-BOND 1030's moisture cure silicone polymer system allows it to cure to the touch in 24hrs and provides a robust conductive bond over a wide range of application temperatures.

For best adhesion results, CHO-BOND 1030 should be used in conjunction with CHO-SHIELD 1086 primer. Typical applications include bonding, repair, and attachment of EMI gaskets, and sealing around EMI vents and windows.




### Features and Benefits:

| | |
|---|---|
| • One component | • Easy to use, no weighing or mixing required. |
| • Silver plated copper filler | • Good conductivity 0.050 ohm-cm. |
| • No VOCs | • Minimal shrinkage. |
| • Moisture cure silicone | • Flexible, 30 minute working life, rapid skin formation, > 200 psi lap shear strength, 24 hr handling time, wide range of application temperatures. 1 week for full cure. |
| • Non corrosive cure mechanism | • No corrosive by-products generated during curing to damage substrate. |
| • Medium paste | • Can be used on overhead or vertical surfaces. |

### Contact Information:

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## CHO-BOND 1030 - Product Information

### Table 1 Typical Properties

| CHO-BOND 1030 | | |
|---|---|---|
| **Typical Properties** | **Typical Values** | **Test Method** |
| Polymer | Silicone | N/A |
| Filler | Silver-Plated Copper | N/A |
| Mix Ratio, A : B (by weight) | 1-part | N/A |
| Color | Light Gray | N/A (Q) |
| Consistency | Medium Paste | N/A (Q) |
| Maximum DC Volume Resistivity | 0.050 ohm-cm | CHO-95-40-5555* (Q/C) |
| Minimum Lap Shear Strength** | 200 psi (1379 kPa) | CHO-95-40-5300* (Q/C) |
| Minimum Peel Strength** | 8.0 lb./inch (1401 N/m) | CHO-95-40-5302* (Q/C) |
| Specific Gravity | 3.8 | ASTM D792 (Q/C) |
| Hardness | 77 Shore A | ASTM-D2240 (Q/C) |
| Continuous Use Temperature | - 55°C to 200°C (-67 °F to 392 °F) | N/A (Q) |
| Elevated Temperature Cure Cycle | None | N/A |
| Room Temperature Cure | 1 week*** | N/A (Q) |
| Working Life | 0.5 hour | N/A (Q) |
| Shelf Life, unopened | 6 months @ 25°C (77°F) | N/A (Q) |
| Minimum thickness recommended | N/A | N/A |
| Maximum thickness recommended | 0.010 in (0.25 mm) | N/A |
| Volatile Organic Content (VOC) | 0 g/l | Calculated |
| Theoretical Coverage Area at 0.010" Thick per Pound (454 grams) | 775 in$^2$ (5000 cm$^2$) | N/A |
| Theoretical Coverage - Length of an 1/8" Diameter Bead per Pound (454 grams) | 50 feet (15.2 m) | N/A |

**Note:** N/A – Not Applicable, (Q/C) - Qualification and Conformance Test, (Q) - Qualification Test
* This test Method is available from Parker Chomerics.
** Minimum values listed are based on using the CHO-SHIELD 1086 primer that typically comes bundled with the CHO-BOND.
*** Cure is sufficient for handling in 24 hours. Full specification properties are developed after 1 week (168 hours) at room temperature.

### Table 2 Ordering Information

| Product | Weight (grams) | Packaging | Part Number | Primer Included |
|---|---|---|---|---|
| CHO-BOND 1030 | 113.4 | 1.5 fluid ounce aluminum foil tube | 50-02-1030-0000 | 1086 |
| | 113.4 | 1.5 fluid ounce aluminum foil tube | 50-02-1030-1000 | No |
| | 454 | 6 fluid ounce SEMCO cartridge | 50-01-1030-0000 | 1086 |

Please refer to Parker Chomerics Surface Preparation and CHO-BOND Application documents for information regarding the proper surface preparation, primer application (if required), and use of these compounds.

**www.chomerics.com**
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